

CLAIMS

1. A method of manufacturing a wafer assembly comprising a chip wafer onto which a cover wafer is deposited, the chip wafer comprising an active face and an inactive face, the active face comprising chip elements, the cover wafer being provided with a chip-element-receiving cavity located above a chip element, the method comprising the following steps:
 - a cover-wafer-depositing step, in which a cover wafer is deposited on the active face so as to obtain a wafer assembly, the cover wafer being provided with a plurality of chip-receiving cavities, a chip-receiving cavity being located above a chip element, the cover wafer being made of an organic material;
 - a wafer assembly thinning step, in which the inactive face of the chip wafer is thinned.
2. The method according to claim 1, wherein the method further comprises a chip-fixing step, in which a chip is fixed in a chip-receiving cavity.
3. The method according to claim 1, wherein the cover-wafer is made of a photosensitive material.
4. The method according to claim 3, wherein the photosensitive material comprises Benzo cyclo Butène.
5. The method according to claim 3, wherein the photosensitive material comprises a polyimide.

6. The method according to claim 3, wherein the photosensitive material comprises an epoxy-based material.
7. The method according to claim 2, wherein the method further
5 comprises a wafer-assembly-cutting step, in which the wafer assembly is cut so as to obtain a plurality of chip assembly, a chip assembly comprising a chip element onto which a chip is fixed.
8. The method according to claim 2 or 3, wherein the chip elements are
10 GSM chips.
9. The method according to claim 2 or 3, wherein the chips are RF chips.
10. The method according to claim 2 or 3, wherein the chips are DPA
15 chips.
11. Method of manufacturing a portable device comprising a support layer provided with a cavity, the method comprising a chip-assembly-fixing step, in which a chip-assembly according to claim 7 is fixed in the
20 cavity.
12. A chip assembly according to claim 7.